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| | Applicant(s): T. Akamatsu et al | |
| | Filing Date: Herewith | Group Art Unit: Unassigned ²³¹⁹ |

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| <table border="0"> <tr> <td>Examiner</td> <td><u>John</u></td> <td>Date Considered</td> <td>9-22-00</td> </tr> </table> | | | Examiner | <u>John</u> | Date Considered | 9-22-00 |
| Examiner | <u>John</u> | Date Considered | 9-22-00 | | | |